

**PRELIMINARY** 

July 1998

# FM27LV010L 1,048,576-Bit (128Kx8) Low Voltage, Low Power EPROM

## **General Description**

The FM27LV010 is a low-power 1Mbit, 3.3V-only one-time-programmable (OTP) read-only memory (EPROM), organized into 128K words with 8 bits per word. Any byte can be accessed in less than 150ns, eliminating the need for WAIT states in high-performance microprocessor systems. The FM27LV010 has separate Output Enable ( $\overline{OE}$ ) and Chip Enable ( $\overline{CE}$ ) controls which eliminate bus contention issues.

The FM27LV010 is one member of a low voltage EPROM family which range in densities from 512Kb to 1Mb.

#### **Features**

- Read Access Time: 150ns■ Single 3.3V Power Supply
- Low Standby Current: 1µA (Typical)

- Programming Voltage +12.75V
- Typical programming time 50µs
- Low Power CMOS Operation
- 15mA Operation (Max.)
- CMOS-and TTL-Compatible I/O
- High-Reliability CMOS Technology
- Latch-Up Immunity to 100mA from -1V to V<sub>CC</sub> + 1V
- Two-Line Control (OE & CE)
- Standard Product Identification Code
- JEDEC Standard Pinout
  - 32-pin PDIP
  - 32-pin PLCC
- 32-pin TSOP (Type 1)
- Commercial and Industrial Temperature Ranges

# **Block Diagram** INPUT/ CE/PGM CONTROL OUTPUT **→** 00 - 07 ŌĒ **LOGIC BUFFERS** 1024 Y-DECODER Y-SELECT A0-A16 ADDRESS : 1M BIT **INPUTS** X-DECODER CELL 1024 **MATRIX** Vcc GND -DS500095-1

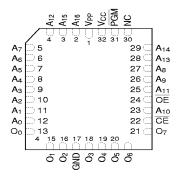
# Commercial Temperature Range (0°C to +70°C) $V_{CC}$ = 5V $\pm$ 10%

Parameter/Order Number	Access Time (ns)				
FM27LV010 N, T, V 150 L	150				

### **Pin Names**

Pin Name	Function
A <sub>0</sub> -A <sub>16</sub>	Addresses
O <sub>0</sub> -O <sub>7</sub>	Outputs
PGM	Program
OE	Output Enable
NC	No Connect
CE	Chip Enable

## **PLCC**



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# Industrial Temperature Range (-40°C to +85°C) $V_{CC}$ = 5V $\pm$ 10%

Parameter/Order Number	Access Time (ns)
FM27LV010 NE, TE, VE 150 L	150

Package Types:

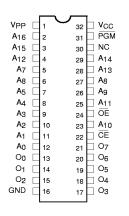
N = Plastic DIP Package

T = TSOP Package

V = PLCC Package

All packages conform to the JEDEC standard

## **PDIP**



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## **TSOP**

			_
A <sub>11</sub> □	1	32	⊃ OE
A <sub>9</sub> ⊏	2	31	P A <sub>10</sub>
A <sub>8</sub> □	3	30	□ CE
A <sub>13</sub> □	4	29	□ O <sub>7</sub>
A <sub>14</sub> □	5	28	□ O <sub>6</sub>
NC □	6	27	□ O <sub>5</sub>
PGM □	7	26	□ O <sub>4</sub>
V <sub>CC</sub> □	8	25	□ O <sub>3</sub>
V <sub>PP</sub> □	9	24	□ GND
A <sub>16</sub> □	10	23	02
A <sub>15</sub> □	11	22	01
A <sub>12</sub> □	12	21	- O₀
A <sub>7</sub> □	13	20	□ A <sub>0</sub>
A <sub>6</sub> □	14	19	P A1
A <sub>5</sub> □	15	18	□ A <sub>2</sub>
A <sub>4</sub> □	16	17	□ A3

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# **Absolute Maximum Ratings** (Note 1)

Storage Temperature -65°C to +125°C

All Input Voltage except A9

with Respect to Ground -0.6V to +7V

V<sub>PP</sub> and A9 with Respect to Ground -0.6V to +13.5V

V<sub>CC</sub> Supply Voltage with

Respect to Ground -0.6V to +7V

**ESD Protection** 

(MIL St. 883, Method 3015.2) >2000V

All Output Voltages with Respect to Ground

-0.6V to  $V_{\rm CC}$  + 0.5V

## **Operating Range**

Range	Temperature (T <sub>C</sub> )	V <sub>cc</sub>	Tolerance
Commercial	0°C to +70°C	+3.3V	± 0.3V
Industrial	-40°C to +85°C	+3.3V	± 0.3V

## **Read Operation**

## **DC Electrical Characteristics**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -0.4mA	2.4		V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.0mA		0.45	V
V <sub>IH</sub>	Input High Voltage		2.0	V <sub>CC</sub> + 0.5	V
V <sub>IL</sub>	Input Low Voltage		-0.3	0.8	V
I <sub>LI</sub>	Input Leakage Current	V <sub>IN</sub> = 0 to V <sub>CC</sub>	-5	5	μΑ
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 0 to V <sub>CC</sub>	-10	10	μΑ
I <sub>CC3</sub>	V <sub>CC</sub> Power-Down Current	$\overline{CE} = V_{CC} \pm 0.3V$		10	μΑ
I <sub>CC2</sub>	V <sub>CC</sub> Standby Current	CE = V <sub>IH</sub>		0.6	mA
I <sub>CC1</sub>	V <sub>CC</sub> Active Current	$\overline{CE} = V_{IL}$ , $f = 5MHz$ , $I_{OUT} = 0mA$		15	mA
I <sub>PP</sub>	V <sub>PP</sub> Supply Current Read	CE = OE = V <sub>IL</sub> , V <sub>PP</sub> = V <sub>CC</sub>		100	μΑ

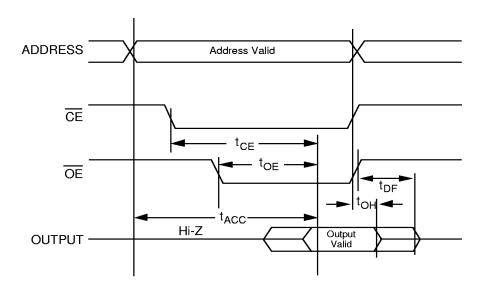
## **AC Electrical Characteristics**

Symbol	Parameter	Min	Max	Unit
t <sub>ACC</sub>	Address to Output Delay		150	ns
t <sub>CE</sub>	CE to Output Delay		150	ns
t <sub>OE</sub>	OE to Output Delay		50	ns
t <sub>DF</sub>	OE or CE High to Output Float, whichever occurred first		40	ns
t <sub>OH</sub>	Output Hold from Address, CE or OE, Whichever Occurred First	0		ns

# Capacitance $T_A = 25$ °C, f = 1MHz

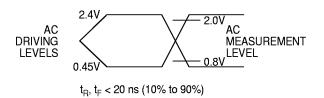
Symbol	Parameter	Conditions	Тур	Max	Units
C <sub>IN</sub>	Input Capacitance Except OE/V <sub>PP</sub>	V <sub>IN</sub> = 0V	8	12	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	8	12	pF
$V_{PP}$	OE/V <sub>PP</sub> Input Capacitance	$V_{IN} = 0V$	18	25	pF

# **AC Waveforms for Read Operation**

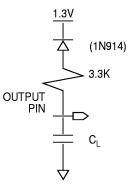


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# **Output Test Waveforms and Measurements**



# **Output Test Load**



**Note:**C<sub>L</sub> = 100pF including jig capacitance

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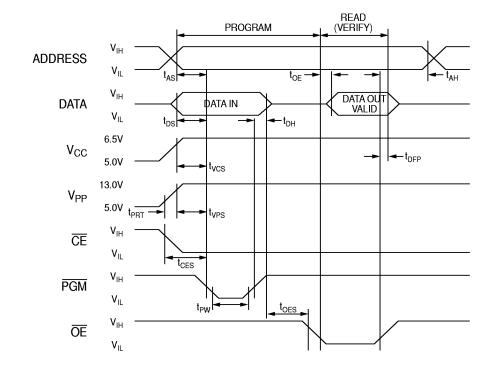
# **DC Programming Characteristics**

			Lin	nits		
Sumbol	Parameter	<b>Test Conditions</b>	Min	Max	Units	
ILI	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		5.0	μΑ	
V <sub>IL</sub>	Input Low Level		-0.5	0.8	V	
V <sub>IH</sub>	Input High Level		2.4	V <sub>CC</sub> + 0.5	V	
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.45	V	
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400μA	2.4		V	
I <sub>CC2</sub>	V <sub>CC</sub> Supply Current			40	mA	
I <sub>PP2</sub>	V <sub>PP</sub> Supply Current	CE = PGM = V <sub>IL</sub>		10	mA	
V <sub>ID</sub>	A9 Product ID Voltage		11.5	12.5	V	
V <sub>PP</sub>	Programming Supply Voltage		12.5	13.0	V	
V <sub>CC</sub>	Power Supply Voltage		6.25	6.75	V	

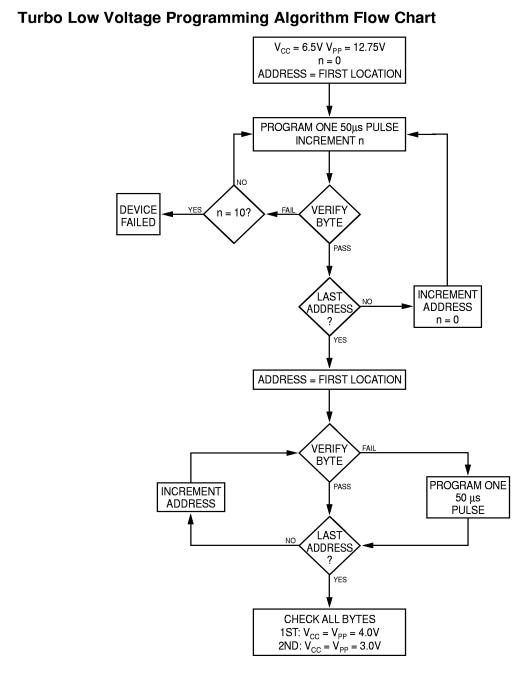
# Switching Programming Characteristics (T $_{A}$ = +25 $^{\circ}$ $\pm$ 5 $^{\circ}C)$

Symbol	Parameter	Min	Max	Units
t <sub>AS</sub>	Address Setup Time	1		μs
t <sub>OES</sub>	OE/V <sub>PP</sub> Setup Time	1		με
t <sub>DS</sub>	Data Setup Time	1		με
t <sub>AH</sub>	Address Hold Time	0		μs
t <sub>DH</sub>	Data Hold Time	1		με
t <sub>DFP</sub>	Output Enable to Output Float Delay	0	130	ns
t <sub>VPS</sub>	V <sub>PP</sub> Setup Time	1		με
t <sub>PW</sub>	PGM Program Pulse Width	20	105	με
t <sub>vcs</sub>	V <sub>CC</sub> Setup Time	1		μs
t <sub>CES</sub>	CE Setup Time	1		μs
t <sub>OE</sub>	Data Valid from OE		150	ns

# **Programming Waveforms**



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Figure 1

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Note: National Semiconductor NM27C010 Fast Programming Algorithm may also be used.

## **Functional Description**

## **Device Operation**

The modes of operation of the EPROM are listed in Table 1. The power supplies required are  $V_{\rm CC}$  and  $\overline{\rm OE/V_{PP}}.$  The  $\overline{\rm OE/V_{PP}}$  power supply must be at 12.75 during the three programming modes, and must be at 3.3V in the other three modes. The  $V_{\rm CC}$  power must be at 6.5V during the three programming modes, and at 3.3V in the other three modes.

#### **Read Mode**

The EPROM has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable (CE/PGM) is the power control and should be used for device selection. Output Enable (OE/V<sub>PP</sub>) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t<sub>ACC</sub>) is equal to the delay from  $\overline{CE}$  to output (t<sub>CE</sub>). Data is available at the outputs t<sub>OE</sub> after the falling edge of  $\overline{OE}$ , assuming that  $\overline{CE}$  has been low and addresses have been stable for at least t<sub>ACC</sub> - t<sub>OE</sub>.

#### Standby Mode

The FM27LV010 has CMOS standby mode which reduces the maximum  $V_{CC}$  current to 1µA (typical). It is placed in CMOS standby when  $C\bar{E}$  is at  $V_{CC}\pm 0.3V$ . The FM27LV010 also has a TTL standby mode which reduces the maximum  $V_{CC}$  current to 0.6 mA. It is placed in TTL standby when CE is at  $V_{IH}$ . When in standby mode, the outputs are in a high-impedance state, independent of the OE input.

## **Two-Line Output Control Function**

To accommodate multiple memory connections, a two-line control function is provided to allow for:

- 1. Low memory power dissipation,
- 2. Assurance that output bus contention will not occur.

It is recommended that  $\overline{CE}$  be decoded and used as the primary device-selection function, while  $\overline{OE}$  be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

## **Programming**

Caution: Exceeding 13.5V on pin 22 (OE/ $V_{PP}$ ) will damage the EPROM.

Initially, and after each erasure, all bits of the EPROM are in the "1's" state. Data is introduced by selectively programming "0's" into the desired bit locations. Although only "0's" will be programmed, both "1's" and "0's" can be presented in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure.

The EPROM is in the programming mode when the OE/ $V_{PP}$  power supply is at 12.75V. it is required that at least a 0.1 $\mu$ f capacitor be placed across  $V_{CC}$  to ground to suppress spurious voltage transients which may damage the device. The data to be programmed is applied 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.

When the address and <u>data are stable</u>, an active low, TTL program pulse is applied to the CE/PGM input. A program pulse must be applied at each address locaiton to be programmed.

The EPROM is programmed with the Turbo Low Voltage Programming Algorithm shown in Figure 1. Each Address is programmed with a series of 50µs pulses until it verifies good, up to a maximum of 10 pulses. Most memory cells will program with a single 50µs pulse. The Turbo Low Voltage Programming Algorithm will be available in early Quarter 1, 1998. Until this program is installed the EPROM may be programmed using National Semiconductor NM27C010 Fast Programming Algorithm.

The EPROM must not be programmed with a DC signal applied to the  $\overline{\text{CE}/\text{PGM}}$  input.

Programming multiple EPROM in parallel with the same data can be easily accomplished due to the simplicity of the programming requirements. Like inputs of the parallel EPROM may be connected together when they are programmed with the same data. A low level TTL pulse applied to the CE/PGM input programs the paralleled EPROM.

## **Program Inhibit Mode**

Programming of multiple FM27LV010 in parallel with different data is also easily accomplished by using the Program Inhibit Mode. Except for  $\overline{\text{CE}}$ , all like inputs of the parallel FM27LV010 may be common. A TTL low-level program pulse appled to a FM27LV010  $\overline{\text{CE}}$  input with  $\overline{\text{OE}/\text{V}_{PP}} = 12.75 \pm 0.25 \text{V}$  will program that FM27LV010. A high-level  $\overline{\text{CE}}$  input inhibits the other FM27LV010 from being programmed.

### **Program Verify Mode**

Verification should be performed on the programmed bits to determine that they were correctly programmed. The verification should be performed with  $\overline{OE/V_{PP}}$  and  $\overline{CE}$  at  $V_{IL}$ . Data should be verified at  $t_{DV}$  after the falling edge of  $\overline{CE}$ .

## **System Consideration**

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a  $0.1\mu F$  ceramic capacitor (high frequency, low inherent inductance) should be used on each device between  $V_{CC}$  and  $V_{SS}$  to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a  $4.7\mu F$  bulk electrolytic capacitor should be used between  $V_{CC}$  and  $V_{SS}$  for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

### Mode Selection

The modes of operation of the FM27LV010 are listed in Table 1. A single 3.3V power supply is required in the read mode. All inputs are TTL levels except for  $V_{\rm PP}$  and A9 for device signature.

## Functional Description (Continued)

**Table 1. Mode Selection** 

Mode	CE	OE	PGM	Α0	<b>A</b> 1	A9	V <sub>PP</sub>	Output
Read	V <sub>IL</sub>	V <sub>IL</sub>	X (Note 2)	Х	X	Х	V <sub>CC</sub>	D <sub>OUT</sub>
Output Disable	V <sub>IL</sub>	V <sub>IH</sub>	Х	Х	X	Х	V <sub>CC</sub>	High Z
Standby (TTL)	V <sub>IH</sub>	Х	Х	Х	Х	Х	V <sub>CC</sub>	High Z
Standby (CMOS)	$V_{CC} \pm 0.3V$	Х	Х	Х	Х	Х	V <sub>CC</sub>	High Z
Program (Note 4)	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	Х	Х	Х	V <sub>PP</sub>	D <sub>IN</sub>
Program Verify	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	Х	Х	Х	V <sub>PP</sub>	D <sub>OUT</sub>
Program Inhibit	V <sub>IH</sub>	Х	Х	Х	Х	Х	V <sub>PP</sub>	High Z
Manufacturer Code (Note 3)	V <sub>IL</sub>	Х	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	VH (Note 1)	V <sub>CC</sub>	
Device Code (Note 3)	$V_{IL}$	Х	V <sub>IH</sub>	V <sub>IH</sub>	V <sub>IH</sub>	VH (Note 1)	V <sub>CC</sub>	

Note 1:  $VH = 12.0V \pm 0.5V$ . Note 2:  $X = Either V_{IH}$  or  $V_{IL}$ 

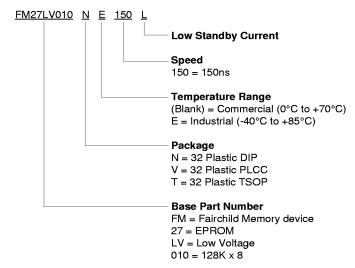
Note 3: For Manufacturer Code and Device Code, A1 =  $V_{IH}$  When A1 =  $V_{IL}$ , both codes will read 7F.

Note 4: See DC Programming Characteristics for  $V_{\rm PP}$  voltage during programming.

Table 2. Manufacturer's Identification Code

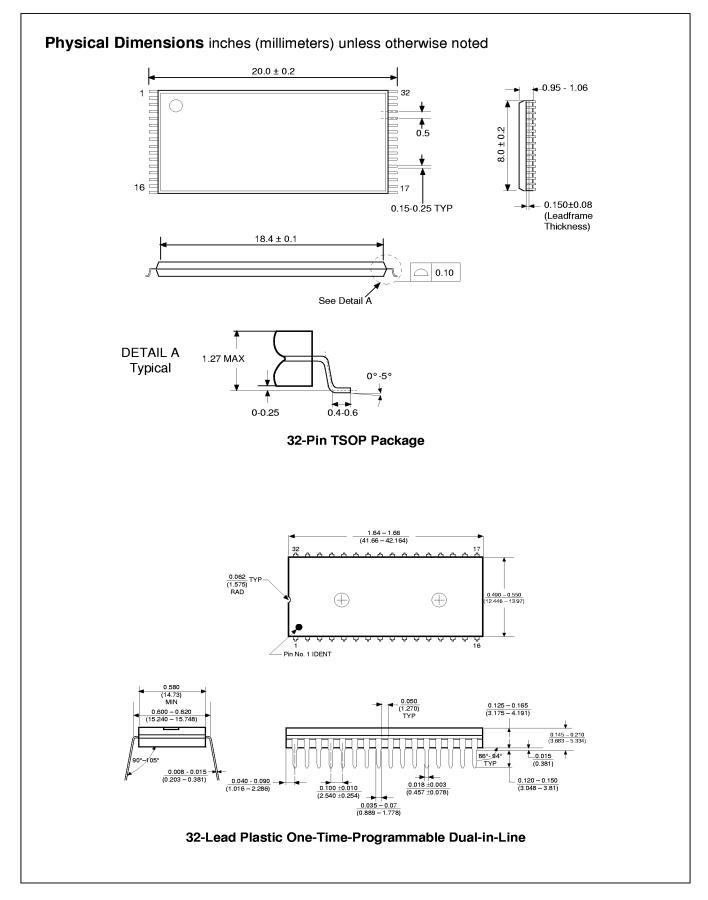
Pins Code	A 0	A 1	O 7	O 6	O 5	O 4	O 3	O 2	O 1	O 0	Hex Data
Manufacturer	0	1	0	0	0	1	1	1	0	0	1C
Device Type	1	1	0	1	0	0	0	0	0	1	01
Continuation	0	0	0	1	1	1	1	1	1	1	7F
	1	0	0	1	1	1	1	1	1	1	7F

## **Ordering Information**



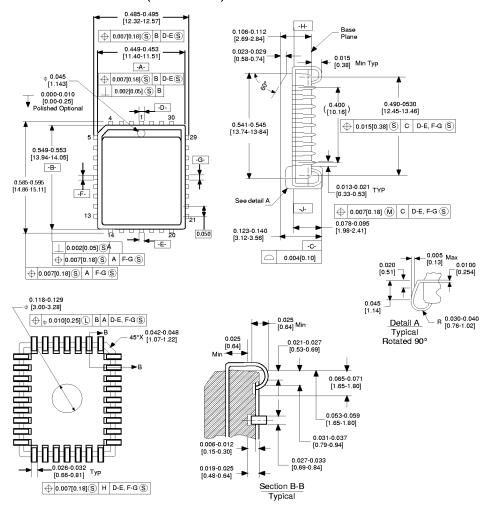
DS500095-9

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## Physical Dimensions inches (millimeters) unless otherwise noted



32-Lead Plastic Leaded Chip Carrier (PLCC) Package Number VA32A

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